The Institute for Interconnecting and Packaging Electronic Circuits 2215 Sanders Road • Northbrook, IL 60062



IPC-TM-650 TEST METHODS MANUAL

1 Scope This is a non-destructive test method for quickly and accurately measuring hole pattern locations.

2 Applicable Documents None

3 Test Specimen Qualification inspection is performed on the standard IPC test board (A-41, A-42, A-43, A-44). Conformance testing is performed on production product.

4 Equipment/Apparatus A CECO INSTRUMENT, Linear Micrometer model ##TA510CP3 with an accuracy of 0.005 mm per 25.4 mm, or equivalent, shall be used. Any optical, optical/mechanical or mechanical means is acceptable within the accuracy limits specified.

Number 2.2.19	
Subject Measuring Hole Patt	ern Location
Date 12/87	Revision
Originating Task Group N/A	

5 Procedure

5.1 Place the specimen face down on the measuring table and align the board's tooling holes with the table pin locating holes.

5.2 Measure all holes for location accuracy, with respect to the datum (Registration to the Master Drawing).

6 Report Report all hole measurements.